


APPLICATION DATA SHEET

Electronic Version v14

Stylesheet Version v14.0

Title of Invention	[WAFER STRUCTURE AND BUMPING PROCESS THEREOF]		
Application Type : regular, utility Attorney Docket Number : 11579-US-PA			
Correspondence address: Customer Number: 31561 			
Priority Data: Doc.No: 92118830; Country -TW ; Date: 2003-07-10 us-priority-claimed			
Inventor Information: <u>Inventor 1:</u> Applicant Authority Type: Inventor Citizenship: TW Name prefix: Mr. Given Name: Min-Lung Family Name: Huang Residence: City of Residence: Kaohsiung Country of Residence: TW Address-1 of Mailing Address: 10F, No.8, Alley 2, Lane 33, Address-2 of Mailing Address: Ting-yung St., San-min Chu City of Mailing Address: Kaohsiung State of Mailing Address: Postal Code of Mailing Address: Country of Mailing Address: TW Phone: Fax: E-mail:			
Attorney Information: practitioner(s) at Customer Number:			

31561



as my attorney(s) or agent(s) to prosecute the application identified above, and to transact all business in the United States Patent and Trademark Office connected therewith.